

# SOT1629-1

plastic, ball grid array; 1295 bumps; 1.0 mm pitch; 37.5 mm x 37.5 mm x 3.19 mm body

31 August 2018

Package information

## 1 Package summary

|                                       |                       |
|---------------------------------------|-----------------------|
| <b>Terminal position code</b>         | B (bottom)            |
| <b>Package type descriptive code</b>  | BGA1295               |
| <b>Package style descriptive code</b> | BGA (ball grid array) |
| <b>Package body material type</b>     | P (plastic)           |
| <b>JEDEC package outline code</b>     | MS-034                |
| <b>Mounting method type</b>           | S (surface mount)     |
| <b>Issue date</b>                     | 24-12-2015            |
| <b>Manufacturer package code</b>      | 98ARE10748D           |

**Table 1. Package summary**

| Parameter                      | Min   | Nom  | Max   | Unit |
|--------------------------------|-------|------|-------|------|
| package length                 | -     | 37.5 | -     | mm   |
| package width                  | -     | 37.5 | -     | mm   |
| seated height                  | 2.88  | 3.19 | 3.53  | mm   |
| package height                 | 0.684 | 0.76 | 0.836 | mm   |
| nominal pitch                  | -     | 1    | -     | mm   |
| actual quantity of termination | -     | 1295 | -     |      |



plastic, ball grid array; 1295 bumps; 1.0 mm pitch; 37.5 mm x 37.5 mm x 3.19 mm body

2 Package outline

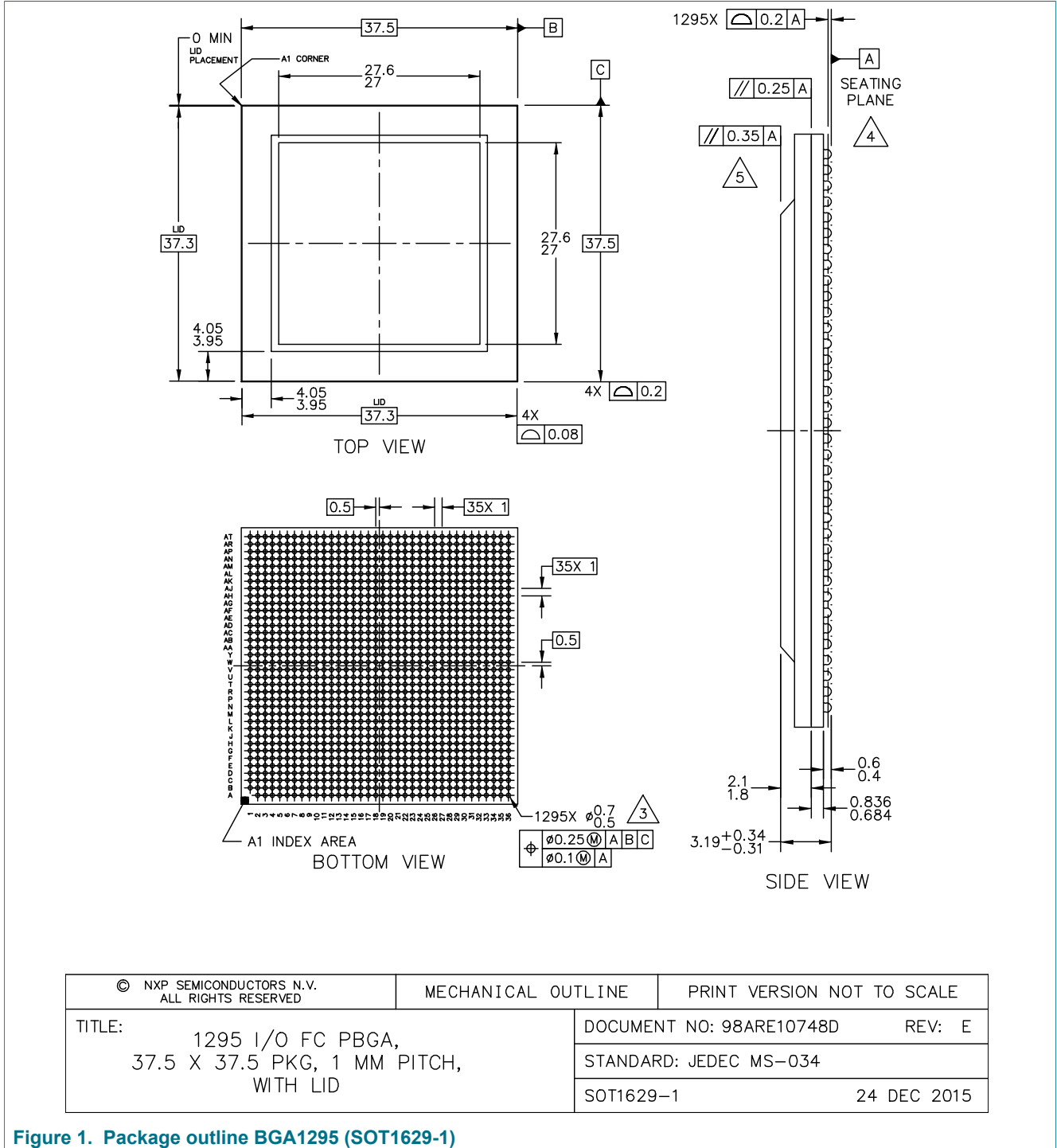


Figure 1. Package outline BGA1295 (SOT1629-1)

plastic, ball grid array; 1295 bumps; 1.0 mm pitch; 37.5 mm x 37.5 mm x 3.19 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

|   |                    |                            |             |
|---|--------------------|----------------------------|-------------|
| © NXP SEMICONDUCTORS N.V.<br>ALL RIGHTS RESERVED                        | MECHANICAL OUTLINE | PRINT VERSION NOT TO SCALE |             |
| TITLE:<br>1295 I/O FC PBGA,<br>37.5 X 37.5 PKG, 1 MM PITCH,<br>WITH LID |                    | DOCUMENT NO: 98ARE10748D   | REV: E      |
|   |                    | STANDARD: JEDEC MS-034     |             |
|   |                    | SOT1629-1                  | 24 DEC 2015 |

Figure 2. Package outline note BGA1295 (SOT1629-1)

### 3 Legal information

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